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first and second outer layers, each including substrate material; and
 at least one inner layer disposed between said first and second outer layers,
 said inner layer including at least one conductive trace disposed on substrate
 material proximate to an edge of the interconnection device and being accessible
 for direct electrical connection.”

Thus, the applicant's claimed interconnection device includes an inner layer with a
 conductive trace disposed on substrate material. In contrast, Inasaka discloses an exposed
 conductive layer – not a conductive trace. Inasaka therefore fails to teach or suggest the
 Applicant's invention as set forth in independent Claim 1. Claims 2 – 6, 12, and 13 are
 dependent upon claim 1; thus Inasaka fails to teach or suggest the invention as set forth in all the
 pending claims. The Applicant therefore respectfully requests that this rejection be withdrawn.

2. Claims 1 – 3 and 13 were rejected under 35 USC 102(e) as being anticipated by U.S.
 Patent No. 6,061,246 to Oh et al. (“Oh”). This rejection is respectfully traversed. Applicant's
 independent claim 1 recites an interconnection device comprising...

“first and second outer layers, each including substrate material; and
 at least one inner layer disposed between said first and second outer layers,
 said inner layer including at least one conductive trace disposed on substrate
 material proximate to an edge of the interconnection device and being accessible
for direct electrical connection.”

In contrast, the conductive traces disclosed in Oh are not accessible for direct electrical
 connection. Oh states at Column 5 lines 13 – 18:

“The conductive lines 141 on flexible layer 122 extend from the conductive via
 holes 125 onto the flexible extension 140 and are electrically connected to the
 LCD panel 110 using anisotropic conductive film 132, solder or other electrical
 connection techniques”.

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Thus, Oh fails to teach or suggest the Applicant's inner layer including at least one conductive trace ... being accessible for direct electrical connection, as set forth in independent Claim 1. Claims 2 - 3 and 13 are dependent on Claim 1; thus, Oh fails to teach or suggest the Applicant's invention as set forth in Claims 1 - 3 and 13. The Applicant therefore respectfully requests that this rejection be withdrawn.

Applicants have made a diligent effort to place the claims in condition for allowance. However, should there remain unresolved issues that require adverse action, it is respectfully requested that the Examiner telephone Mary Steubing, Applicants' Attorney at 978-264-6664 so that such issues may be resolved as expeditiously as possible.

For these reasons, and in view of the above amendments, this application is now considered to be in condition for allowance and such action is earnestly solicited.

Respectfully Submitted,

FAX RECEIVED

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Date

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MARKED-UP CLAIMS

1. An interconnection device comprising:
first and second outer layers, each including substrate material; and
at least one inner layer disposed between said first and second outer layers, said inner layer including at least one conductive trace disposed on substrate material proximate to an edge of the [printed wiring board] interconnection device and being accessible for direct electrical connection.
2. The interconnection device of claim 1 wherein said conductive inner layer trace extends outward from the edge of the [printed wiring board] interconnection device.
3. The interconnection device of claim 1 wherein at least a portion of said first outer layer is removed to provide access to said conductive inner layer trace.
4. The interconnection device of claim 1 wherein at least one conductive protrusion is formed on said conductive inner layer trace.
5. The interconnection device of claim 4 wherein said protrusion is malleable.
6. The interconnection device of claim 4 wherein said protrusion is resilient.
12. The interconnection device of claim 1 wherein said inner layer substrate material is a ceramic.
13. The interconnection device of claim 1 wherein said inner layer substrate material is organic.

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REPLACEMENT PAGES

1. An interconnection device comprising:
first and second outer layers, each including substrate material; and
at least one inner layer disposed between said first and second outer layers, said inner layer including at least one conductive trace disposed on substrate material proximate to an edge of the interconnection device and being accessible for direct electrical connection.
2. The interconnection device of claim 1 wherein said conductive inner layer trace extends outward from the edge of the interconnection device.
3. The interconnection device of claim 1 wherein at least a portion of said first outer layer is removed to provide access to said conductive inner layer trace.
4. The interconnection device of claim 1 wherein at least one conductive protrusion is formed on said conductive inner layer trace.
5. The interconnection device of claim 4 wherein said protrusion is malleable.
6. The interconnection device of claim 4 wherein said protrusion is resilient.
12. The interconnection device of claim 1 wherein said inner layer substrate material is a ceramic.
13. The interconnection device of claim 1 wherein said inner layer substrate material is organic.